



## MiniMRP ELECTRONICS PACKAGING

---

DISTRIBUTED, INTEGRATED MODULAR PACKAGING . . . MINIATURIZED FOR GROUND DEFENSE APPLICATIONS

The Modular Electronics Architecture, Based on ARINC 836A Standards, Saves Weight, Reduces Package Size, and Increases Design Flexibility Over Existing Architectures

## Now Configurable to Your Custom Application

### Increased Computing Power in a Smaller Package

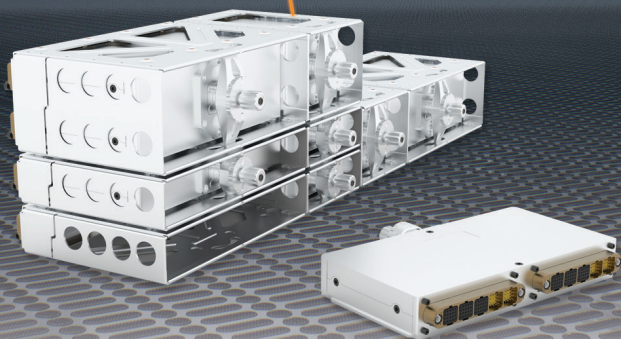
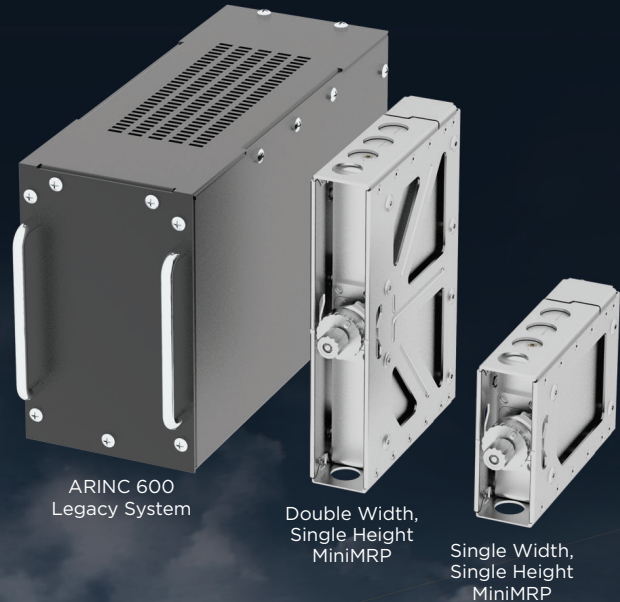
MiniMRP is the Next generation of electronics packaging hardware, putting ever-increasing computing power into smaller packages at lower costs.

### Small Form Factor Devices

The ability to interconnect small-form-factor electronic devices, either directly or over a network, enables distributed systems that replace traditional centralized systems.

### DMC-M: Modular Connectivity

- Standardized Multi-Cavity - EN4165
- Quick Change - Compact - Lightweight
- Full Range of Modules Available  
Signal - Power - RF - Optical



### Distributed Architecture

- Distributed Electronics Packaging for Flexible Design in a Smaller, Lighter Package
- Easily Deployed Throughout the System
- Distributed Around a Fiber Optic or Copper Backbone



## Putting Intelligence Closer to the Action

A distributed electronics packaging system creates flexible capabilities in a smaller, lighter package. The Mini Modular Rack Principle (MiniMRP), standardized in ARINC 836A, is fast emerging as one of the leading choices for packaging of distributed systems. The MiniMRP provides standardized modules that can be easily deployed throughout a system, allowing information to be collected and distributed around a fiber optic or copper backbone.

## Modularity Simplifies Configuration

By creating a series of standard modules, the MiniMRP system allows a mix-and-match approach to design and deployment. Modules can be used singly or combined as needed to create specific functionality throughout the system, whether it be for a ground vehicle or fighter jet. Module upgrades, replacements, or expansions are easily accomplished.

## Lower Costs through Standardization

By providing compact, standardized modules, MiniMRP enhances the ability to distribute embedded computing functions throughout the aircraft. Standardization of both connector inserts and modular enclosure sizes provide a commonality of components within a system and across a wide range of different platforms.

## Lower Costs – COTS Components

Designers of electronic systems can take advantage of commercial off-the-shelf (COTS) components, thereby streamlining the design cycle to enable a faster time to market. Additionally, they give designers access to well-established, high-volume products that can lower costs through economies of scale. Standardization creates a competitive ecosystem.

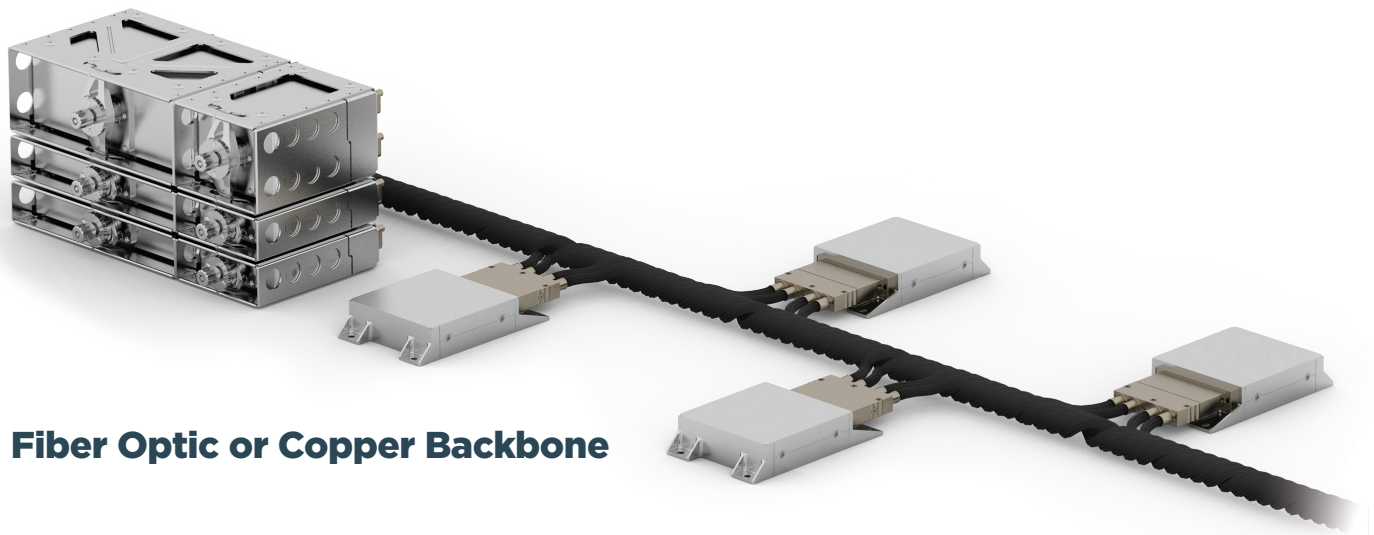
## Fiber Optic or Copper Backbone

### Space Advantage

The small size of the MiniMRP system can help to optimize the design of the interior of a military vehicle or aircraft. MiniMRP provides the ability to upgrade MiniMRP units without changing out the entire system architecture. The system architecture can be designed to meet the customer requirements.

### Meets Military Needs

MiniMRP mounts connector systems in accordance with the EN4165 European military aerospace standard. It is similar to MIL-DTL-38999 in performance, but with added benefits of a small footprint and versatility. The standard finish of the enclosure and tray components is Surtec 650V, which meets MIL-DTL-81706B and MIL-DTL-5541F for bare corrosion and accommodates ruggedized applications.



# MiniMRP Electronics Packaging

## Latched Enclosure



## Product Features

- Vibration resistant latching mechanism
- Toolless operation
- Electrically conductive and corrosion resistant surface finish
- Interfaces with latched tray (Pg 6)
- Lightweight

## TE Part Numbering System

### Enclosure Size

- SWSH-L** Single Width, Single Height
- DWSH-L** Double Width, Single Height
- SWDH-L** Single Width, Double Height
- DWDH-L** Double Width, Double Height

### Enclosure Material

- A** Aluminum with SurTec 650V surface treatment

### Connector Cut-Out

- 1** Type 5 Bay (for Standard DMC Module inserts)
- 2** Type 5 Bay (for Low Profile DMC Module inserts)
- 3** Blank Plate

SWSH-L - A - 1

Note: Connector Shell and Blank plate to be ordered separately

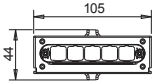
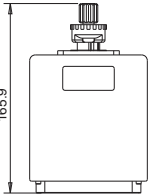
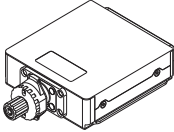

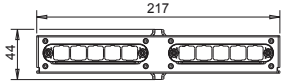
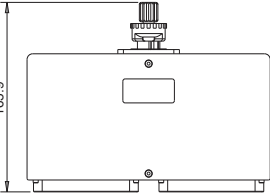
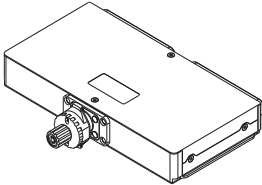
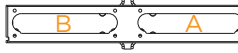
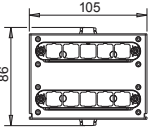
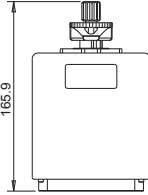
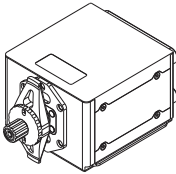
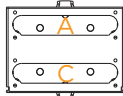
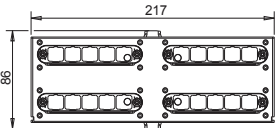
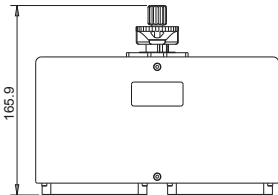
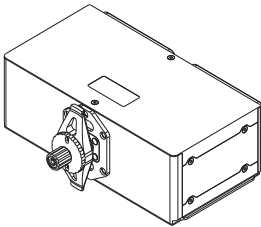
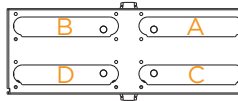
Table inserted for connector shell part references (See pg 10)

5-bay connector shells are supplied with disassembled components which require a tool to mount and dismount. Please refer to your TE Sales representative.

# MiniMRP Electronics Packaging

## Latched Enclosure

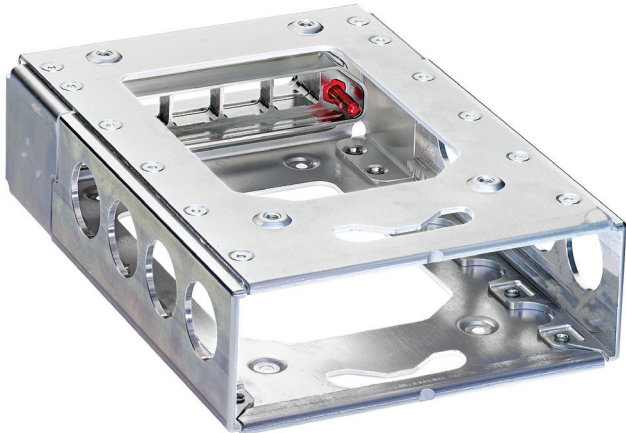
## Configurations

	Front View	Top View	ISO View	Connector Positioning (View on mating face)
<b>Single Width Single Height (SWSH)</b>				
<b>Double Width Single Height (DWSH)</b>				
<b>Single Width Double Height (SWDH)</b>				
<b>Double Width Double Height (DWDH)</b>				

Measurements are in mm.

# MiniMRP Electronics Packaging

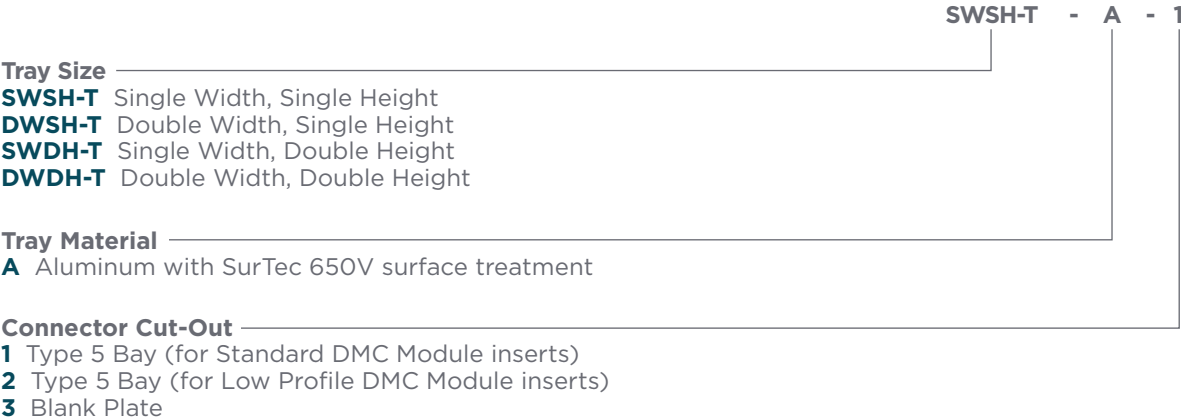
## Latched Tray



## Product Features

- Optimized to be stiff yet lightweight
- Ability to stack together different tray sizes using built-in vibration resistant threads
- Electrically conductive and corrosion resistant surface finish
- Externally mounted connector shell reduces installation time
- Optional Mounting-Plate allows attachment of the tray to structure per ARINC 836A

## TE Part Numbering System



Note: Connector Shell and Blank plate to be ordered separately

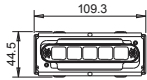
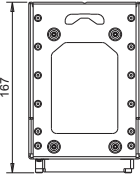
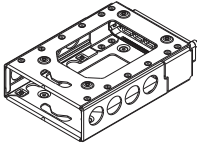

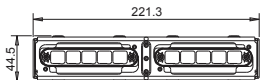
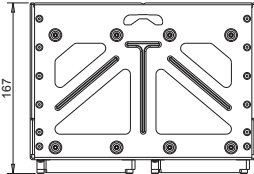
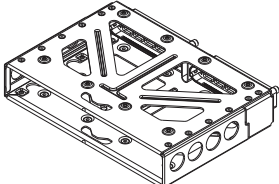

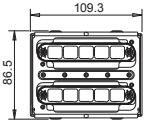
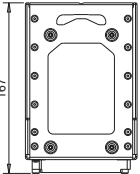
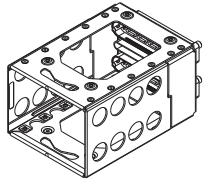
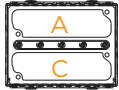
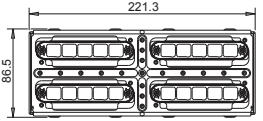
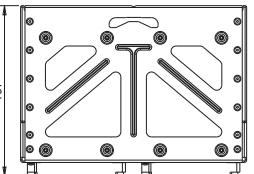
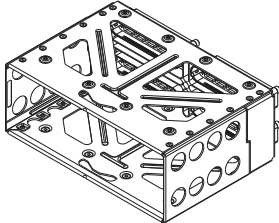
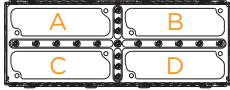
Table inserted for connector shell part references (See pg 10)

5-bay connector shells are supplied with disassembled components which require a tool to mount and dismount. Please refer to your TE Sales representative.

# MiniMRP Electronics Packaging

## Latched Tray

## Configurations

	Front View	Top View	ISO View	Connector Positioning (View on mating face)
<b>Single Width Single Height (SWSH)</b>				
<b>Double Width Single Height (DWSH)</b>				
<b>Single Width Double Height (SWDH)</b>				
<b>Double Width Double Height (DWDH)</b>				

Measurements are in mm.

# MiniMRP Electronics Packaging

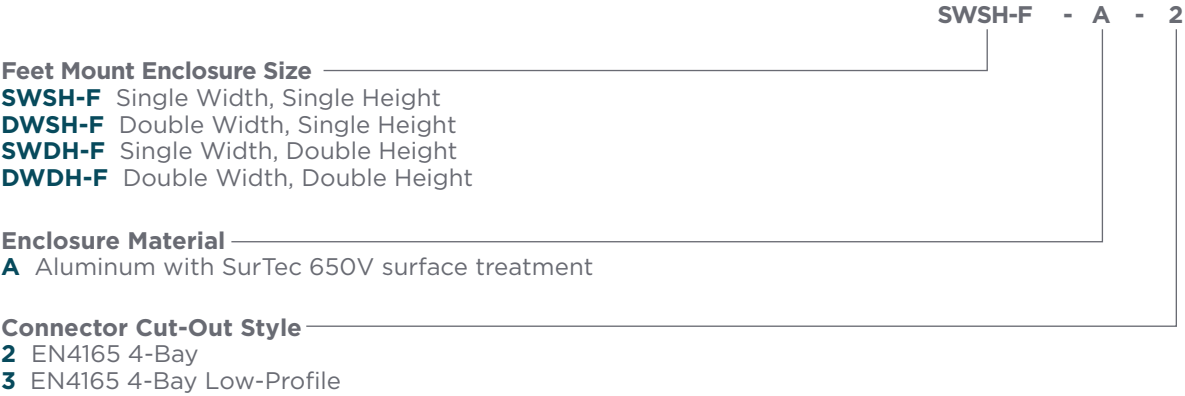
## Feet Mount Enclosure



## Product Features

- Provides an alternative where space is at a premium
- Further weight reduction (without tray)
- Electrically conductive and corrosion resistant surface finish
- Not available with EN4165 Type 5 Bay connector shell

## TE Part Numbering System



Note: Connector Shell and Blank plate to be ordered separately

4-bay EN4165 connector receptacles are supplied with a disassembled keying component which requires a tool to mount and dismount. Please refer to your TE Sales representative and/or the Deutsch DMC-M Series Multicavity EN4165 Connector catalog.

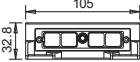
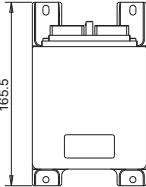
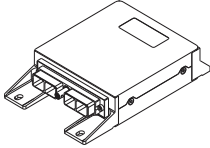

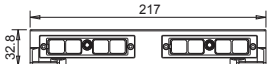
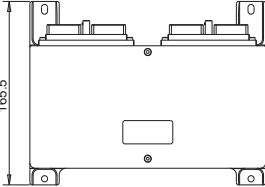
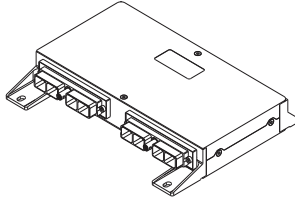
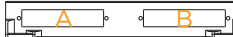
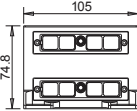
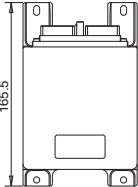
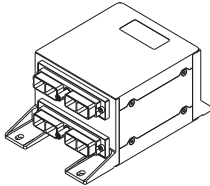
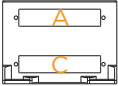
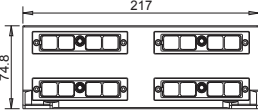
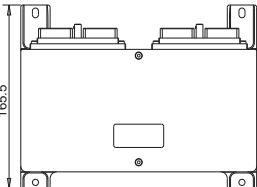
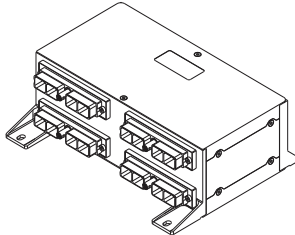
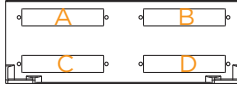
Table inserted for connector shell part references (See pg 10)



# MiniMRP Electronics Packaging

## Feet Mount Enclosure

## Configurations

	Front View	Top View	ISO View	Connector Positioning (View on mating face)
<b>Single Width Single Height (SWSH)</b>				
<b>Double Width Single Height (DWSH)</b>				
<b>Single Width Double Height (SWDH)</b>				
<b>Double Width Double Height (DWDH)</b>				

Measurements are in mm.

# MiniMRP Electronics Packaging

## 5 BAY CONNECTOR SHELLS

Part Number	Description
2403869-1	5 Bay Aluminum Receptacle Assembly Standard Module – 5 Bay Enclosure Aluminum Connector shell (for Standard DMC Module Inserts)
2403808-1	5 Bay Aluminum Receptacle Assembly – 5 Bay Enclosure Aluminum Connector shell (for Low Profile DMC Module Inserts)
2401090-1	5 Bay Aluminum Extended Tray Plug Assembly – 5 Bay Tray Aluminum Connector Shell (for DMC Module Inserts)
DMC-LP 84 AM 01 A	4 Bay Aluminum Connector shell (for Low Profile DMC Module Inserts)
DMC-MD 85 AM 01	4 Bay Aluminum Connector shell (for Standard DMC Module Inserts)

## Customization Options

### Integrated Solutions

TE can support fully integrated solutions with embedded electronics, fiber optics and wireless connectivity



### Thermal

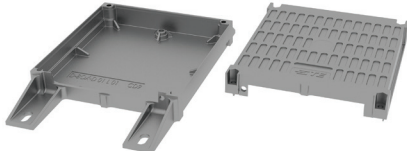
Integrated design features can be tailored to support the thermal management requirements



### Connectivity

Custom connector interfaces can be easily integrated for the specific application, such as:

- Single Module EN4165
- 369 Series Connectors
- Non-Aerospace Connectors



### Material

Lightweight polymer/hybrid variants are in development, including:

- Fully Composite Design
- Hybrid Metal and Composite Design



### Design

Enclosures can be modified for custom requirements including sizes, mount positions and external features, such as antennas

# MiniMRP Electronics Packaging

## Advantages of MiniMRP-Based Distributed Systems

### Reduced Package Size

MiniMRP modules are smaller than existing MRP modules, allowing them to fit into smaller spaces.

### Reduced Weight

MiniMRP modules are made of lightweight aluminum or even lighter weight composite materials. Distributed modules also reduce the amount of copper cabling throughout the system. MiniMRP components, in combination with an integrated modular electronics architecture, allows connectivity through a lightweight, high-speed fiber-optic or copper backbone to simplify the cabling system further.

### Reduced Complexity through Common Components

Standardized modular enclosures and interconnect components enable users to pick from a wide variety of standard choices.

### Increased Flexibility

The ability to mix and match modules simplifies the task of meeting specific application goals.

### Easier Deployment and Upgrades

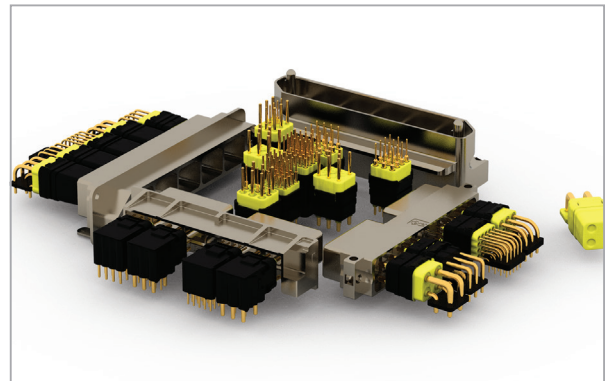
Configuration is easy by specifying the type and location of modules. The MiniMRP modules provide quick and easy tool-less installation, and changes, maintenance, and upgrades are simply accomplished by swapping out modules.



## One Concept Fits Multiple Platforms

While the ARINC 836 MiniMRP is aimed at cabin systems in commercial aircraft, it is also finding use in military applications. The advantages of TE's MiniMRP modules make them ideal for application in military aircraft, helicopters, and unmanned aerial vehicles:

- Easy installation and maintenance
- Flexible modularity and industry standardization



## DEUTSCH DMC-M Series Connectors

**DEUTSCH DMC-M connectors from TE Connectivity (TE) are an excellent connector solution for MiniMRP modules.**

Standardized in European Standard EN4165, DMC-M connectors provide a modular, flexible, and reliable system.

- Available in both multi-cavity and single-module configurations
- Compact, lightweight connectivity
- Composite housings, aluminum wire capability, fiber optics, higher densities, and shunting configurations available
- DMC-M connectors are offered in a variety of layouts, and in sizes 8, 12, 16, 20 and 22
- Contacts can be crimped on copper wire, aluminum wire, or PCB mounting

Empower Engineers to Solve Problems, Moving the World Forward.

AMP | AGASTAT | CII | DEUTSCH | DRI | HARTMAN | KILOVAC  
MICRODOT | NANONICS | POLAMCO | Raychem | SEACON

## CONNECT WITH US

We make it easy to connect with our experts and are ready to provide all the support you need. Visit [te.com/support](https://te.com/support) to chat with a Product Information Specialist.

## QUALITY STARTS WITH THE RIGHT APPLICATION TOOLING

Creating a quality crimp connection is essential to delivering high performance and reliability in extreme environments. From low to high volume wire processing, TE has you covered with a full range of application tooling and a global field service team.

- [View all application tooling](#)
- [Connect with our experts to find the right tool for your application](#)

### [te.com/MiniMRP](https://te.com/MiniMRP)

AMP, AGASTAT, CII, DEUTSCH, DRI, HARTMAN, KILOVAC, MICRODOT, NANONICS, POLAMCO, Raychem, SEACON, TE, TE Connectivity, and TE connectivity (logo) are trademarks owned or licensed by TE Connectivity. All other logos, products and/or company names referred to herein might be trademarks of their respective owners.

The information given herein, including drawings, illustrations and schematics which are intended for illustration purposes only, is believed to be reliable. However, TE Connectivity makes no warranties as to its accuracy or completeness and disclaims any liability in connection with its use. TE Connectivity's obligations shall only be as set forth in TE Connectivity's Standard Terms and Conditions of Sale for this product and in no case will TE Connectivity be liable for any incidental, indirect or consequential damages arising out of the sale, resale, use or misuse of the product. Users of TE Connectivity products should make their own evaluation to determine the suitability of each such product for the specific application.

© 2023 TE Connectivity All Rights Reserved.

2382236-1 05/24

### MiniMRP ELECTRONICS PACKAGING

TE Connectivity  
Aerospace, Defense & Marine  
2900 Fulling Mill Road  
Middletown, PA 17057